

# Single-chip Type with Built-in FET type Switching Regulators





# Flexible Step-down Switching Regulator with Built-in Power MOSFET

**BD8649EFV** No.10027EAT45

#### Description

The BD8649EFV is a synchronous step-down switching regulator that integrates 2 low resistances N-channel MOSFETs. It achieves 3A continuous output current over a wide input supply range. Current mode operation provides fast transient response and easy phase compensation.

#### Feature

- 1) Synchronous rectification with built-in FET type DC/DC converter
- 2) 3.0A output current
- 3) Range of operation power-supply voltage 4.5V~18V
- 4) Reference voltage FB 0.8V±1%
- 5) Programmable frequency 100kHz~600kHz
- 6) Over current protection function
- 7) Thermal shutdown function
- 8) Under voltage protection
- 9) Soft start time out function / Soft start delay circuit
- 10) Programmable OFFLATCH time

#### Applications

FPD, DVD, HDD Recorder, STB, Amusement, Other

#### ● Absolute maximum rating (Ta=25°C)

| Parameter              | Symbol                | Ratings                        | Unit |
|------------------------|-----------------------|--------------------------------|------|
| Input supply voltage   | V <sub>IN</sub>       | 20                             | V    |
| BOOT terminal voltage  | V <sub>BOOT</sub>     | 28                             | V    |
| EN terminal voltage    | V <sub>EN</sub>       | GND-0.3 ∼ V <sub>IN</sub> +0.3 | V    |
| Input terminal voltage | $V_{\text{INP}}^{*1}$ | GND-0.3 ∼ 7                    | V    |
| SW terminal voltage    | V <sub>SW</sub>       | GND-0.3 ∼ V <sub>IN</sub> +0.3 | V    |
| Output current         | I <sub>OUT</sub>      | 3.5 <sup>*2</sup>              | Α    |
| Power dissipation      | Pd                    | 3.2 <sup>*2</sup>              | W    |
| Operating temperature  | Topr                  | -20 ~ 85                       | လူ   |
| Storage temperature    | Tstg                  | -55 <b>~</b> 150               | ပ္   |

<sup>\*1</sup> V<sub>INP</sub> Application terminal: SS/DELAY, FB, FC, RT, PSET

#### Operation condition

| Parameter            | Symbol          | Ratings |      |      | Unit |
|----------------------|-----------------|---------|------|------|------|
| Farameter            |                 | Min.    | Тур. | Max. | Uill |
| Input supply voltage | V <sub>IN</sub> | 4.5     | -    | 18.0 | V    |
| Output current       | lout            | -       | -    | 3.0  | Α    |

<sup>\*</sup> This product is not designed for protection against radioactive rays.

<sup>\*2 (70</sup>mm×70mm, thickness 1.6mm, and four layer glass epoxy substrates)When mounting substrate and the package back exposure part are connected with solder

Operating at higher than Ta=25°C, 25.6mW shall be reduced per 1

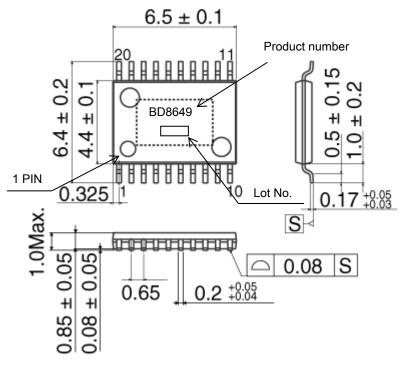
# ●Electrical characteristic

(Unless otherwise noted Ta=25°C, V<sub>IN</sub>=12V, V<sub>EN</sub> = 3V)

| Parameter                                  | Symbol                | Limits |       |       | UNIT | Condition               |  |
|--|-----------------------|--------|-------|-------|------|-------------------------|--|
| Farameter                                  | Symbol                | Min.   | Тур.  | Max.  | UNIT | Condition               |  |
| V <sub>IN</sub> supply current (operating) | I <sub>Q_active</sub> | -      | 1.5   | 2.5   | mA   | V <sub>FB</sub> = 0.75V |  |
| V <sub>IN</sub> supply current (standby)   | I <sub>Q_stby</sub>   | -      | 0.8   | 1.2   | mA   | V <sub>EN</sub> = 0V    |  |
| Reference voltage (VREF)                   | $V_{FB}$              | 0.792  | 0.800 | 0.808 | V    | FB-FC Short             |  |
| Oscillation frequency                      | fosc                  | 270    | 300   | 330   | kHz  | R <sub>RT</sub> = 56kΩ  |  |
| High side FET ON resistance                | R <sub>HFET</sub>     | -      | 110   | 160   | mΩ   | I <sub>SW</sub> = -1A   |  |
| Low side FET ON resistance                 | R <sub>LFET</sub>     | -      | 110   | 160   | mΩ   | I <sub>SW</sub> = 1A    |  |
| UVLO voltage                               | V <sub>UVLO</sub>     | 3.8    | 4.0   | 4.2   | V    | V <sub>IN</sub> Sweep   |  |
| SW leak current                            | I <sub>LSW</sub>      | -      | 0     | 5     | μA   | V <sub>EN</sub> = 0V    |  |
| EN terminal H threshold voltage            | V <sub>ENH</sub>      | 1.6    | -     | -     | V    |                         |  |
| EN terminal L threshold voltage            | V <sub>ENL</sub>      | -      | -     | 0.4   | V    |                         |  |
| SS/DELAY terminal source current           | I <sub>SSSO</sub>     | 2.8    | 4.0   | 5.2   | μA   | V <sub>SS</sub> = 1V    |  |
| SS/DELAY – FB Offset voltage               | V <sub>SSFBOST</sub>  | 450    | 600   | 750   | mV   | V <sub>SS</sub> = 1V    |  |
| PSET terminal source current               | I <sub>PSET</sub>     | 3.0    | 5.0   | 7.0   | μA   | V <sub>PSET</sub> = 2V  |  |
| PSET terminal threshold voltage            | V <sub>PSET</sub>     | 0.8    | 1.0   | 1.2   | V    |                         |  |

- $V_{FB}$ :FB terminal voltage,  $V_{EN}$ :EN terminal voltage,  $V_{SS}$ :SS/DELAY terminal voltage,  $V_{PSET}$ :PSET terminal voltage,  $R_{RT}$ :RT resistor Current capability should not exceed Pd.

# Package outline dimension



HTSSOP-B20 (Unit: mm)

### ●Reference data

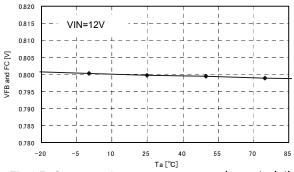


Fig.1 Reference voltage – temperature characteristic

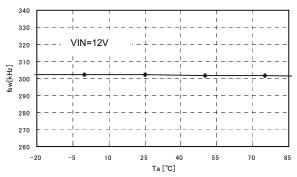


Fig.3 Frequency – temperature characteristic

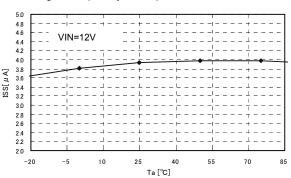


Fig.5 SS/DELAY charge current - temperature characteristic

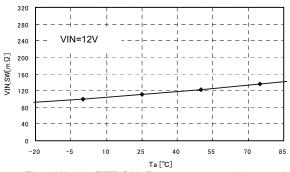


Fig.7 Hi side FET ON\_R - temperature characteristic

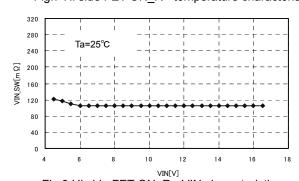


Fig.9 Hi side FET ON\_R - VIN characteristic

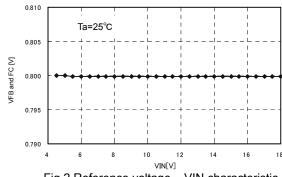
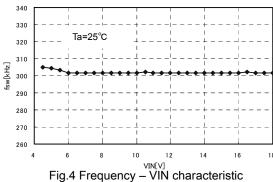


Fig.2 Reference voltage - VIN characteristic



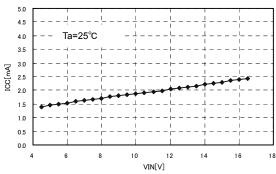


Fig.6 Circuit Current - VIN characteristic

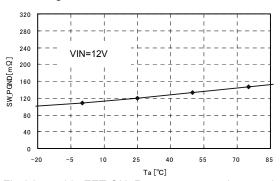
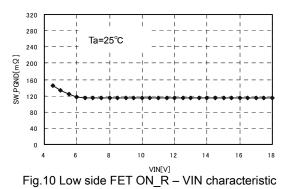


Fig.8 Low side FET ON\_R - temperature characteristic



Technical Note

# ●Block Diagram

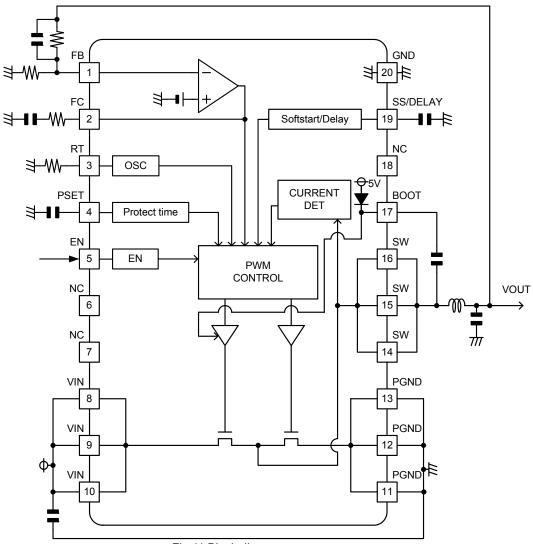


Fig.11 Block diagram

#### Pin Assignment

| 'ın Assıç | IIIIIGIIL |   |     |          |  |
|-----------|-----------|---|-----|----------|--|
| No.       | Symbol    | Description   | No. | Symbol   | Description  |
| 1         | FB        | Feedback terminal                                   |     | PGND     | Power GND terminal                                 |
| 2         | FC        | Phase amends terminal                               |     | PGND     | Power GND terminal                                 |
| 3         | RT        | Frequency adjustment resistance connection terminal | 13  | PGND     | Power GND terminal                                 |
| 4         | PSET      | Adjust OFF LATCH time terminal                      | 14  | SW       | Switching output terminal                          |
| 5         | EN        | Enable input  | 15  | SW       | Switching output terminal                          |
| 6         | NC        | -   | 16  | SW       | Switching output terminal                          |
| 7         | NC        | -   | 17  | воот     | Boot strap terminal                                |
| 8         | VIN       | Power supply input terminal                         | 18  | NC       | -  |
| 9         | VIN       | Power supply input terminal                         | 19  | SS/DELAY | Soft start adjustment capacity connection terminal |
| 10        | VIN       | Power supply input terminal                         | 20  | GND      | Signal GND terminal                                |

BD8649EFV Technical Note

#### Operation description

#### 1 Enable control

The device can be controlled ON/OFF by EN terminal (5 pin) voltage.

An internal circuit starts when VEN reaches 1.6V.

When standing up of VIN is too steep (1msec or less), a defective start might be caused according to the state of Pascon between GND substrate pattern and power supply-when the terminal EN is short-circuited to the terminal VIN and it is used.

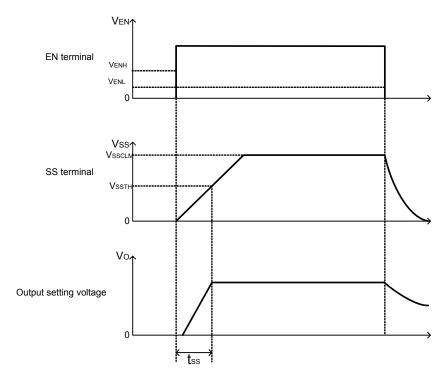


Fig.12 ON/OFF transition wave form in EN controlling

## 2 Soft start time set function

As for BD8649EFV, output can do soft start without overshoot by charging soft start capacity ( $C_{SS}$ ) connected between SS/DELAY (19 pin) and GND (20 pin) terminal.

Also, soft start time (tss) can be set by setting soft start capacity (C<sub>ss</sub>) arbitrarily. (Refer to 5-2 soft start time setting method)

# 3 OSC oscillation frequency setting function

The output oscillation frequency can be set by connecting resistance between terminal RT (3 pin) and GND (range = 100kHz – 600kHz)

The relation between RT terminal resistance and the oscillation frequency follows Fig.13.

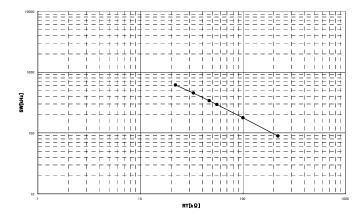


Fig.13 Oscillation frequency setting by RT resistance

5/13

#### Protection function

Protection circuit is effective for destruction prevention due to accident so that avoid using under continuous protection operation.

### 1 Low voltage protection function (LVP)

The voltage of the terminal FB (1pin) is compared with internal reference voltage VREF.

If FB terminal voltage falls below V<sub>LVP</sub> (= VREF -120mV) and the state continues, output changes to low voltage and the state is fixed.

Table 1 output low voltage protection function

| EN terminal        | SS terminal | FB terminal        | Low voltage<br>Protection function | Low voltage<br>Protection operation |
|--------------------|-------------|--------------------|------------------------------------|-------------------------------------|
|                    | >1.4V(typ)  | <v<sub>LVP</v<sub> | Effective                          | ON                                  |
| >V <sub>ENH</sub>  | >1.4v(typ)  | >V <sub>LVP</sub>  | Ellective                          | OFF                                 |
|                    | <1.4V(typ)  | -                  | Invalidity                         | OFF                                 |
| <v<sub>ENL</v<sub> | -           | -                  | Invalidity                         | OFF                                 |

Low voltage protection function is available when SS terminal voltage becomes more than 1.4V (typ) in the transition to ON control (during soft start).

<u>2 Over voltage protection function (OVP)</u>
The voltage of the terminal FB is compared with internal reference voltage VREF.

If FB terminal voltage is over Vovp (=VREF +120mV) and the state is continues, output changes to low voltage and the state is fixed.

Table 2 output low voltage protection function

| EN terminal        | SS terminal  | FB terminal        | Low voltage<br>Protection function | Low voltage<br>Protection operation |
|--------------------|--------------|--------------------|------------------------------------|-------------------------------------|
|                    | > 1 A\//h/m\ |                    | Effective                          | ON                                  |
| >V <sub>ENH</sub>  | >1.4V(typ)   | <v<sub>OVP</v<sub> | Ellective                          | OFF                                 |
|                    | <1.4V(typ)   | -                  | Invalidity                         | OFF                                 |
| <v<sub>ENL</v<sub> | -            | -                  | Invalidity                         | OFF                                 |

Over voltage protection function is available when SS terminal voltage becomes more than 1.4V (typ) in the transition to ON control (during soft start).

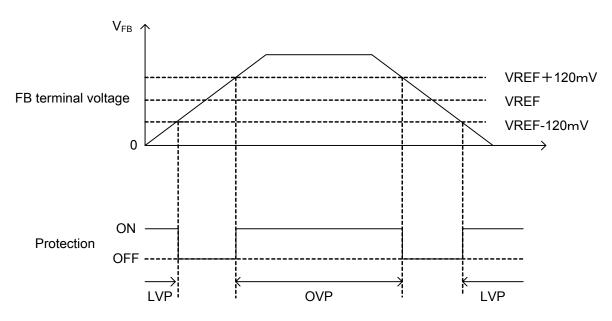


Fig.14 Output voltage error detection range

Technical Note BD8649EFV

#### 3 Under voltage lock out protection (UVLO)

As for BD8649EFV, the power-supply voltage decrease detection protection circuit is built in.

It the input voltage decrease below the UVLO voltage (4.0V typ), the device state changes to the standby mode (Moreover, to prevent the chattering of the output) hysteresis width of 300mV(typ) has been installed in the UVLO cancel voltage.

# 4 RT terminal open/short protection function (RTO/RTS)

RT terminal opening/short protection function prevents the clock from abnormal oscillation.

If RT terminal open/short protection function is detected, output voltage changes to low level and is fixed.

#### 5 Soft start time-out function

If VSS doesn't exceed VSSTH within 75msec (typ) since a soft start began, BD8649EFV controls an off latch. Vo is fixed in a low level.

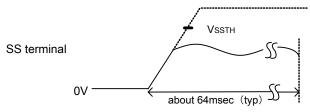


Fig.15 Soft start time-out

### 6 Thermal shut down function

Thermal shut down circuit (TSD circuit) is built into BD8649EFV. When the temperature of the chip exceeds Timax=175, the DC/DC converter is fixed in a low voltage.

TSD function is aimed to shut down IC from thermal reckless driving under an abnormal state to exceed Timax=150. It aims at neither protection nor the guarantee of the set. Therefore, please do not use this function to protect the set.

<u>7 Over current protection function</u>
The over current protection function has been achieved by limiting the current that flows on high side MOSFET.

The current is controlled in every one cycle of the switching frequency. When an abnormal state continues, the output is fixed in a low level.

#### 8 Error detection (off latch) release method

BD8649EFV enters the state of an off latch when the protection function operates.

To release the off latch state, VIN terminal voltage should be changed to less than UVLO level (=4.0V [typ] ) once time.

BD8649EFV Technical Note

#### External parts setting method

#### 1 Output voltage setting method

The output voltage can be arbitrarily set by external resistance.

$$Vo = \frac{(R1+R2)}{R2} VREF$$

Please select the constant of R1 and R2 by this expression.

Please select the current that flows to R1 and R2 to become much smaller than output current.

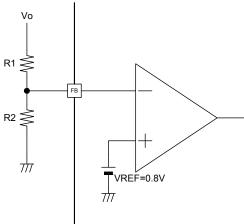


Fig.16 Output voltage setting circuit

#### 2 Soft start time setting method

BD8649EFV can soft start without overshoot because of a charge current to the soft start capacitance (CSS).

The soft start time can be set by connecting soft start capacity (CSS).

When the EN terminal voltage is set VIN\_EN or more, the charge to the capacity between SS/DELAY and GND terminal is begun. The output voltage becomes soft start in proportion to a SS/DELAY terminal voltage rising. When the SS/DELAY terminal voltage exceeds VSSTH, the output voltage is fixed in a setting value.

Please set soft start time (tss) in 1msec-52.5msec.

$$Tvo = TWen(=50\mu s) + \frac{Vost(=0.6V) \times Css}{Iss(=4\mu A)} + \frac{(Vssth - Vost) \times Css}{Iss(=4\mu A)}$$

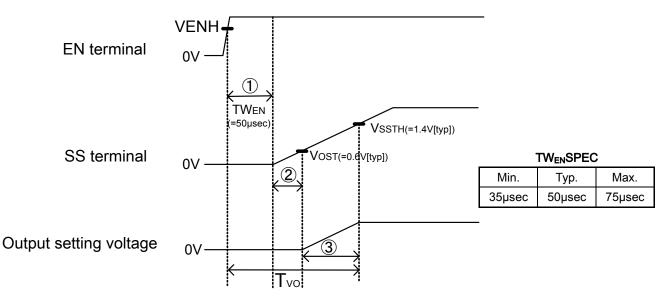


Fig.17 Soft start

#### 3 Selection of inductor (L)

Please select the value of the inductor according to the following expressions.

$$L = \frac{(V_{IN} - V_{OUT}) \times V_{OUT}}{ \triangle I_L \times V_{IN} \times f} \quad [H]$$

( IL: Output ripple current , f: Switching frequency)

\*Please have and select an enough margin so that the current peak should not exceed the ratings current value of the inductor.

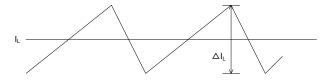


Fig.18 Current of output ripple

### 4 Selection of input capacitor (Cin)

Please use a low ESR input capacitor which can be used with high voltage and ripple current to prevent a big transition voltage.

\*Please put on the input capacitor near side by VIN-PGND.

#### 5 Selection of diode

Please have and set the margin enough to the current rating of the diode for the maximum load current. Moreover, please similarly have and set the margin enough to a ratings reverse-voltage for the maximum input voltage.

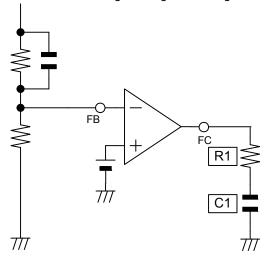


Fig.19 Phase amends part external circuit chart

#### 6 OFFLATCH time setting method

If it continues abnormal state, BD8649EFV output become low voltage and state is fixed.

In this case, the OFFLATCH time can be set by connecting capacitor between PSET and GND. Please select the value of OFFLATCH time according to the following expression. Please set OFFLATCH time in 200µsec~5msec.

$$T_{TM} = \frac{C_{PSET}}{I_{PSET}(5\mu A typ)} [sec] \cdot \cdot \cdot (11)$$

To release the off latch state, EN or VIN terminal voltage should be changed to low level once time.

BD8649EFV Technical Note

# ●Typical application

[Condition]

VOUT = 3.3V

fosc = 550kHz

OFF LATCH time = 500µsec

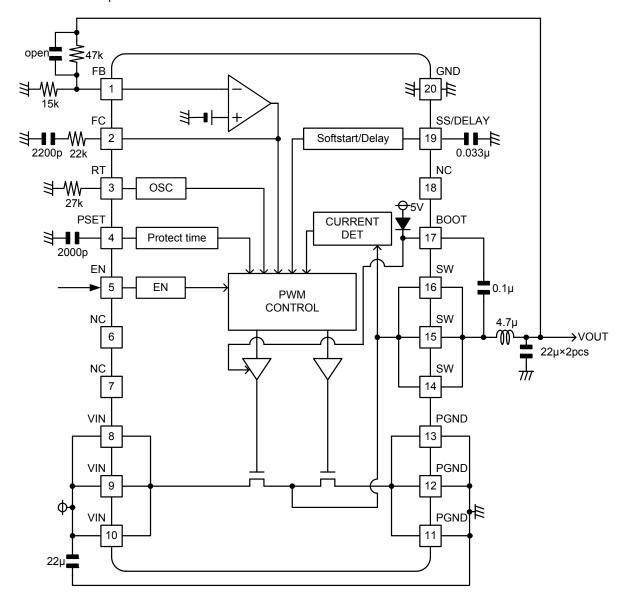


Fig.20 Typical application

# ●I/O equivalence circuit

| 1PIN(FB)                        | 1PIN(FB) 2PIN(FC)   |  |
|---------------------------------|---|--|
| VIN                             | VIN OVIN OVIN OVIN OVIN OVIN OVIN OVIN O  | $\begin{array}{c c} & & & & \\ & & & & \\ & & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ & & & \\ &$ |
| 4PIN(PSET)                      | 5PIN(EN)  | 14,15,16PIN(SW)  |
| 50kΩ PSET  100kΩ  2kΩ  GND  GND | VIN  THE MATERIAL STATE OF THE | SW<br>GND  |
| 17PIN(BOOT)                     | 19PIN(SS/DELAY)   |  |
| VRECS<br>BOOT<br>SW             | 50kΩ \$ SS' DELAY  50kΩ \$ 2kΩ  |  |

#### ■Note for use

BD8649EFV

1. About the absolute maximum rating

Attention is brushed off enough to the quality control, it is likely to destroy when the absolute maximum rating such as impressed voltages (VCC\_IN,DCIN) and ranges (Topr) of the operating temperature as it is exceeded, the mode of breakings of the short or the opening, etc. cannot be specified, and examine it in this IC to give physical measures for safety such as fuses when a special mode that exceeds the absolute maximum rating is assumed.

GND pin voltage

GND terminal should be connected the lowest voltage, under all conditions. And all terminals except SW should be under GND terminal voltage under all conditions including transient situations. If a terminal exists under GND, it should be inserting a bypass route.

3. Power dissipation

If IC is used on condition that the power loss is over the power dissipation, the reliability will become worse by heat up, such as reduced output current capability. Also, be sure to use this IC within a power dissipation range allowing enough of margin.

4. Input supply voltage

Input supply pattern layout should be as short as possible.

5. About the short and the miss-installation between terminals

Note the direction and the miss-registration of IC enough when you install it in the set substrate. IC might destroy it as well as reversely connecting the power supply connector when installing it by mistake. Moreover, there is fear of destruction when the foreign body enters between terminals, the terminal, the power supply, and grandeur and it is short-circuited.

6. About operation in strong electromagnetic field

In use in strong electromagnetic field, note that there is a possibility of malfunctioning.

7. About the inspection by the set substrate

It is likely to suffer stress to IC and discharge electricity every one process when you connect the capacitor with the pin with low impedance when inspecting it in the set substrate. Moreover, detach it after connecting after the power supply is turned off without fail when detaching it to G in the inspection process, inspecting, and turning off the power supply. In addition, be give the earth to the assembly process as a static electricity measures, and careful enough when it transports and you preserve it.

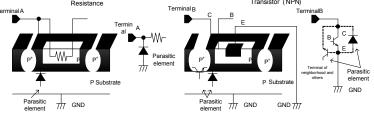
8. About each input terminal

This IC is a monolithic IC which has a P<sup>+</sup> isolations and P substrate to isolate elements each other.

This P layer and an N layer in each element form a PN junction to construct various parasitic elements.

For instance, the potential difference operates in resistance as shown in the figure below when resistance and the transistor connect it with the terminal and the playground (GND) >(terminal B) joint of PN operates as a parasitic diode in playground (GND) >(terminal A) transistor (NPN). In addition, the NPN transistor of parasitism works with N layer of the element of the above-mentioned parasitic diode and the neighborhood and others in transistor (NPN). A parasitic element in IC composition is inevitably formed because of the potential relation.

A parasitic element can operate, the interference with the circuit operation be caused, it malfunction, and, consequently, it cause destruction. Therefore, do not do the usage that a parasitic element operates as a voltage that is lower than the playground (GND; P substrate) is impressed to the input terminal enough. Moreover, do not impress the voltage to the input terminal when you do not impress the power-supply voltage to IC. Give each input terminal to me the voltage below the power-supply voltage or in the guarantee value of an electric characteristic when you similarly impress the power-supply voltage.



Example of IC of simple structure

# 9. Earth wiring pattern

If small signal GND and large current GND exist, disperse their pattern. In addition, for voltage change by pattern wiring impedance and large current not to change voltage of small signal GND, each ground terminal of IC must be connected at the one point on the set circuit board. As for GND of external parts, it is similar to the above-mentioned.

10. About each output terminal

We recommend to put Diode for protection purpose in case of output pin connected with large load of impedance or reserve current occurred at initial and output off.

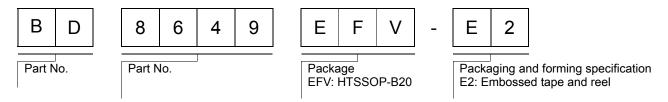
11. Thermal Shut Down Circuit

A temperature control is built in the IC to prevent the damage due to overheat. Therefore, the outputs are turned off when the thermal circuit works.

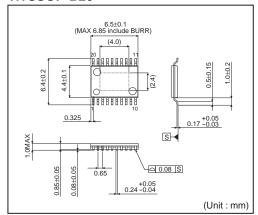
12. Over Output Current Protection

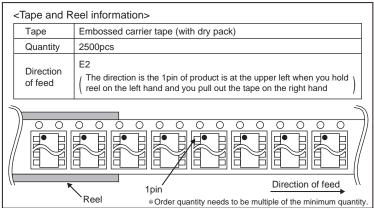
SW Output terminal has over current protection circuit of 5A, with prevents IC from being damage by short circuit at over current. However, It is recommend not to use that continuously operates the protection circuit (For instance, always the load that greatly exceeds the output current ability is connected or the output is short-circuited, etc.) in these protection circuits by an effective one to the destruction prevention due to broken accident.

# Ordering part number



### HTSSOP-B20





#### Notes

No copying or reproduction of this document, in part or in whole, is permitted without the consent of ROHM Co.,Ltd.

The content specified herein is subject to change for improvement without notice.

The content specified herein is for the purpose of introducing ROHM's products (hereinafter "Products"). If you wish to use any such Product, please be sure to refer to the specifications, which can be obtained from ROHM upon request.

Examples of application circuits, circuit constants and any other information contained herein illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.

Great care was taken in ensuring the accuracy of the information specified in this document. However, should you incur any damage arising from any inaccuracy or misprint of such information, ROHM shall bear no responsibility for such damage.

The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM and other parties. ROHM shall bear no responsibility whatsoever for any dispute arising from the use of such technical information.

The Products specified in this document are intended to be used with general-use electronic equipment or devices (such as audio visual equipment, office-automation equipment, communication devices, electronic appliances and amusement devices).

The Products specified in this document are not designed to be radiation tolerant.

While ROHM always makes efforts to enhance the quality and reliability of its Products, a Product may fail or malfunction for a variety of reasons.

Please be sure to implement in your equipment using the Products safety measures to guard against the possibility of physical injury, fire or any other damage caused in the event of the failure of any Product, such as derating, redundancy, fire control and fail-safe designs. ROHM shall bear no responsibility whatsoever for your use of any Product outside of the prescribed scope or not in accordance with the instruction manual.

The Products are not designed or manufactured to be used with any equipment, device or system which requires an extremely high level of reliability the failure or malfunction of which may result in a direct threat to human life or create a risk of human injury (such as a medical instrument, transportation equipment, aerospace machinery, nuclear-reactor controller, fuel-controller or other safety device). ROHM shall bear no responsibility in any way for use of any of the Products for the above special purposes. If a Product is intended to be used for any such special purpose, please contact a ROHM sales representative before purchasing.

If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.



Thank you for your accessing to ROHM product informations. More detail product informations and catalogs are available, please contact us.

# ROHM Customer Support System

http://www.rohm.com/contact/